

Part Number : [877830201](#)
Product Description : 0.60mm Pitch miniDIMM
DDR2 Socket, Surface Mount, 22.5° Angle, 0.76µm
Gold (Au) Plating, Off-White Latches, with Pick-and-
Place Cap, 200 Circuits, 1.8V Voltage Key, Lead-Free
Series Number : 87783
Status : Obsolete
Product Category : Memory Module Connectors



Documents & Resources

Drawings

[877830201 sd.pdf](#)

3D Models and Design Files

[STEP AP242](#)

[SOLIDWORKS](#)

[Creo](#)

[EE-87783-001-001.pdf](#)

[SP-87783-001-001.zip](#)

Specifications

[AS-87782-001-001.pdf](#)

[PS-87783-001-001.pdf](#)

Product Environment Compliance

Compliance

GADSL/IMDS	Not Relevant
China RoHS	 per SJ/T 11365-2006
EU ELV	Not Relevant
Low-Halogen Status	Not Low-Halogen per IEC 61249-2-21
REACH SVHC	Not Contained per D(2023)3788-DC (14 Jun 2023)
EU RoHS	Compliant per EU 2015/863

Compliance Statements

- EU RoHS
- REACH SVHC
- Low-Halogen

Industry Documents

- IPC 1752A Class C
- IPC 1752A Class D
- Molex Product Compliance Declaration
- IEC-62474
- chemSHERPA (xml)

Substances of Interest

- PFAS

EU RoHS Certificate of Compliance

Additional Product Compliance Information

Part Details

General

Status	Obsolete
Category	Memory Module Connectors
Series	87783
Description	0.60mm Pitch miniDIMM DDR2 Socket, Surface Mount, 22.5° Angle, 0.76µm Gold (Au) Plating, Off-White Latches, with Pick-and-Place Cap, 200 Circuits, 1.8V Voltage Key, Lead-Free
Component Type	Socket
JEDEC Outline	MO-258
Product Name	MiniDIMM
UPC	822350075114

Agency

CSA	LR19980
UL	E29179

Electrical

Current - Maximum per Contact	1.0A
Voltage Key	1.8V

Voltage - Maximum	30V
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Physical

Circuits (Loaded)	200
Circuits (maximum)	200
Durability (mating cycles max)	25
Entry Angle	22.5° Angle
Flammability	94V-0
Housing Color	Black
Keying to Mating Part	Yes
Latch Color	Natural (Off-White)
Material - Metal	Copper Alloy
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Material - Resin	High Temperature Thermoplastic
Net Weight	5.444/g
Packaging Type	Tray
PCB Locator	Yes
PCB Retention	Yes
Pitch - Mating Interface	0.60mm
Pitch - Termination Interface	0.60mm
Plating min - Mating	0.762µm
Plating min - Termination	2.540µm
Temperature Range - Operating	-55° to +85°C
Termination Interface Style	Surface Mount

Solder Process Data

Max-Duration	5
Lead-Free Process Capability	REFLOW
Max-Cycle	2
Max-Temp	260

Mates With / Use With

Mates with Part(s)

Description	Part Number
Mates With	JEDEC MO-258 Modules

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Obsolete